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FUJICURE FXD-822

FUJICURE FXD-822 is a modified cycloaliphatic amine intended for use as a room temperature curing agent for liquid epoxy resins special features of this curing agent include its low viscosity, light colour, good colour stability and high gloss.

1. SALES SPECIFICATION

Appearance : clear low viscosity, honey-colored liquid.

Viscosity (25°C) : $300 \sim 700 \text{ mPa} \cdot \text{s}$

Colour (Gardner) : 3 Max. Amine Value (JIS) : 270 ± 10 Specific Gravity (25 / 25°C) : 1.03Flash point (°C) : 115A.H.E.W. : 118

2. RECOMMENTED MIXING RATIO

50~70 parts by weight to 100 parts of Bisphenol-A type epoxy resin whose epoxy equivalent weight is about 190.

3. CURING CHARACTERISTICS

3-1 Epoxy resin : Employed Bisphenol-A type epoxy resin whose epoxy equivalent

weight is about 190.

Total mass : 100 gram Room Temperature : 23° C

Epoxy resin / FUJICURE FX	resin / FUJICURE FXD-822		100/60	100/65
Peak Exothermic Time	(min.)	60	56	51
Peak Exothermic Temperature	$(^{\circ}\!\mathbb{C})$	127	140	146
Gelling Time	(min.)	49	46	44

3-2 Drying characteristics

The drying characteristics of the coated films of the mixtured resin of FXD-822 and the epoxy resin as employed above were measured by RCI drying recorder, as follow;

Epoxy re	sin / FUJICURE I	FXD-822	100 / 55	100 / 60	100 / 65
	Set to touch	(hours)	3.0	2.8	2.7
23°C	Tack free	(hours)	6.5	6.1	5.6
	Dry through	(hours)	14.0	12.0	8.8
	Set to touch	(hours)	6.0	6.5	5.5
5°C	Tack free	(hours)	21.5	21.0	21.0
	Dry through	(hours)	36.5	36.0	35.5

[⊚]film thickness about 150 μm, at 23°C and 5°C



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4. MECHANICAL/PHYSICAL PROPERTIES

Employed Bisphenol-A type epoxy resin whose epoxy equivalent weight is about 190. Curing time=7 days at 23°C

Epoxy resin / FUJICURE	100 / 55	100 / 60	100 / 65	
Tensile Strength	(kgf/mm ²)	5.9	6.1	6.2
Flexural Strength	(kgf/mm^2)	8.4	8.9	8.8
Flexural Modulus	(kgf/mm^2)	3.5×10^2	3.8×10^{2}	3.8×10^{2}
Compressive Strength	(kgf/mm ²)	7.6	7.5	7.5
Izod Impact Strength	(kgf-cm/cm)	1.7	2.0	2.9
Rockwell Hardness	(M Scale)	55	52	55
Shore-d hardness		83	83	82
Heat Distrotion Temperature	$(^{\circ}C)$	45	47	49

5. CHEMICAL RESISTANCE OF THE CURED PRODUCTS

Percentage increase in weight of the cured products of FUJICURE FXD-822 and the same epoxy resin as employed above were measured as follow after curing them at an ambient temperature, and immersing into following chemical substances.

Epoxy resin / FXD-822	100 /40		100 / 50			100 / 60			
Immersion time (days)	1	7	30	1	7	30	1	7	30
Tap Water	0.3	0.9	1.6	0.2	0.9	1.6	0.3	1.0	1.7
5% solution of Salt	0.2	0.7	1.5	0.3	0.8	1.5	0.3	0.8	1.6
10% solution of Caustin soda	0.2	0.7	1.2	0.2	0.6	1.1	0.2	0.7	1.3
10% solution of Ammonia	0.2	0.9	1.7	0.3	0.9	1.8	0.2	0.9	1.9
5% solution of Surfruic Acid	0.4	1.2	2.0	1.5	1.4	2.5	0.6	1.7	3.2
5% solution of Hydrochioric Acid	0.3	0.8	1.5	0.2	0.9	1.7	0.3	1.0	1.9
Kerocene	0.0	0.0	0.0	0.0	0.1	0.2	0.0	0.0	0.1
Isopropylalcohol	-0.1	0.3	0.8	-0.1	0.2	0.8	0.0	0.3	0.8
Metyliso butylietone	0.2	3.2	8.2	0.1	2.0	1.6	0.1	1.4	1.6

6. APPLICATIONS

- 6-1 Solvent free and high solids coatings.
- 6-2 Self leveling floors and mortars.
- 6-3 Water-wipeable tile grouts and lamination.
- 6-4 Reinforced coatings and gel coats.